

wherein the heat spreader is formed by a piece body and a plurality of supporting leads extended downward from a periphery of the piece body;

the printed circuit board has a surface formed thereon a plurality of thermal pads disposed around the die; and

the plurality of supporting leads of the heat spreader are secured to the plurality of thermal pads on the printed circuit board, respectively.

Claim 3, line 1, delete "2" and insert ---1---

Claim 8, line 1, delete "5" and insert ---1---

Claim 9, line 1, delete "5" and insert ---1---

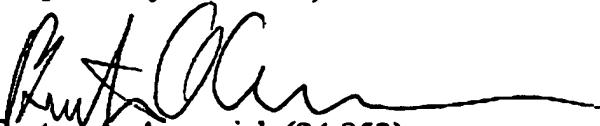
Claim 10, line 1, delete "5" and insert ---1---

Claim 11, line 1, delete "5" and insert ---1---

### REMARKS

Claims 1, 3 and 8-12 are now in the application. The recent telephone conference with the Examiner is hereby noted with appreciation. As discussed, claim 1 has been amended to include recitations from prior claims 2, 5 and 6. None of these amendments is believed to involve any new matter. Accordingly, it is respectfully requested that the foregoing amendments be entered, that the application as so amended receive an examination on the merits, and that the claims as now presented receive an early allowance.

Respectfully submitted,

  
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